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Docket No.: 42P16901

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Matayabas Jr. et al.

Application No.: 10/611,549

Filed: June 30, 2003

For: WIRE-BONDED PACKAGE WITH
ELECTRICALLY INSULATING WIRE
ENCAPSULANT AND THERMALLY
CONDUCTIVE OVERMOLD

Examiner: Ha, Nathan W.

Art Unit: 2814

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUBMISSION OF REPLACEMENT DRAWINGS

Sir:

Submitted herewith are replacement drawings, Figures 1-5 (5 sheets). No new matter has been added. Applicants respectfully request approval of the enclosed replacement drawings for the above-identified application.

Respectfully submitted,

BLAKELY SOKOLOFF TAYLOR & ZAFMAN, LLP

Date: 3-30-06

Todd M. Becker
Todd M. Becker
Reg. No. 43,487

FIRST CLASS CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

on March 30, 2006
Date of Deposit

Yuko Tanaka

Name of Person Mailing Correspondence

Y. Tanaka
Signature

March 30, 2006

Date